



ON Semiconductor®

FDN327N

N-Channel 1.8 Vgs Specified PowerTrench[®] MOSFET

General Description

This 20V N-Channel MOSFET uses ON Semiconductor's high voltage PowerTrench process. It has been optimized for power management applications.

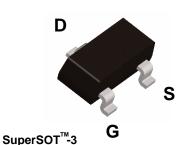
Applications

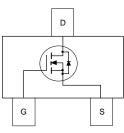
- Load switch
- Battery protection
- Power management

Features

• 2 A, 20 V.

- Low gate charge (4.5 nC typical)
- Fast switching speed
- High performance trench technology for extremely low R_{DS(ON)}





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Absolute Maximum Ratings T_A=25°C unless otherwise noted

| Symbol | Parameter | | | Ratings Ui | |
|-----------------------------------|--------------------------------------|--|-------------|-------------|----------|
| V _{DSS} | Drain-Sour | ce Voltage | | 20 | |
| V _{GSS} | Gate-Source Voltage | | | ± 8 | V |
| I _D | Drain Curre | ent – Continuous | (Note 1a) | 2 | A |
| | | – Pulsed | | 8 | |
| P _D | Power Diss | ipation for Single Operation | (Note 1a) | 0.5 | W |
| | | | (Note 1b) | 0.46 | |
| T _J , T _{STG} | Operating a | Operating and Storage Junction Temperature Range | | -55 to +150 | °C |
| Therma R _{0JA} | al Charac | teristics | t (Note 1a) | 250 | °C/W |
| R _{θJC} | Thermal Resistance, Junction-to-Case | | (Note 1) | 75 | °C/W |
| Packag | e Markin | g and Ordering Inf | ormation | | |
| | Marking | Device R | Reel Size | Tape width | Quantity |

Device MarkingDeviceReel SizeTape widthQuantity327FDN327N7"8mm3000 units

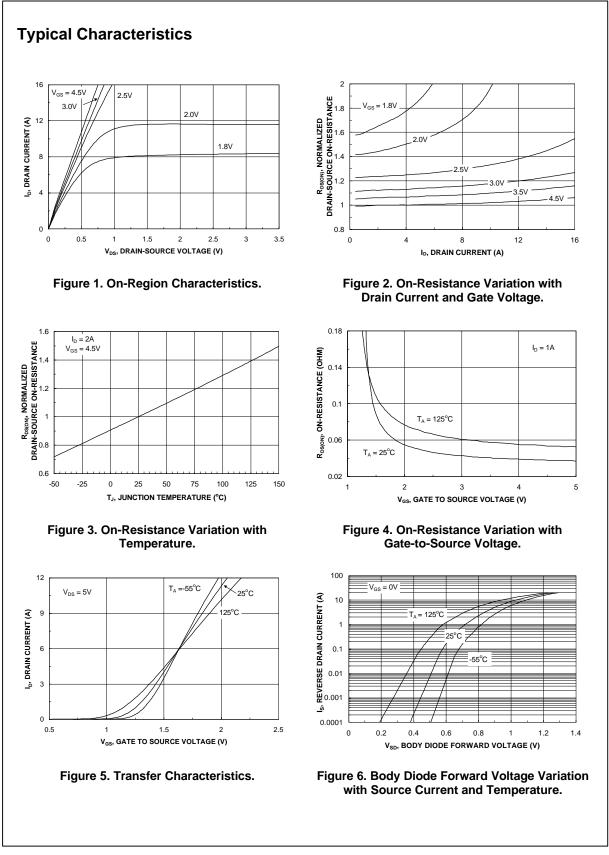
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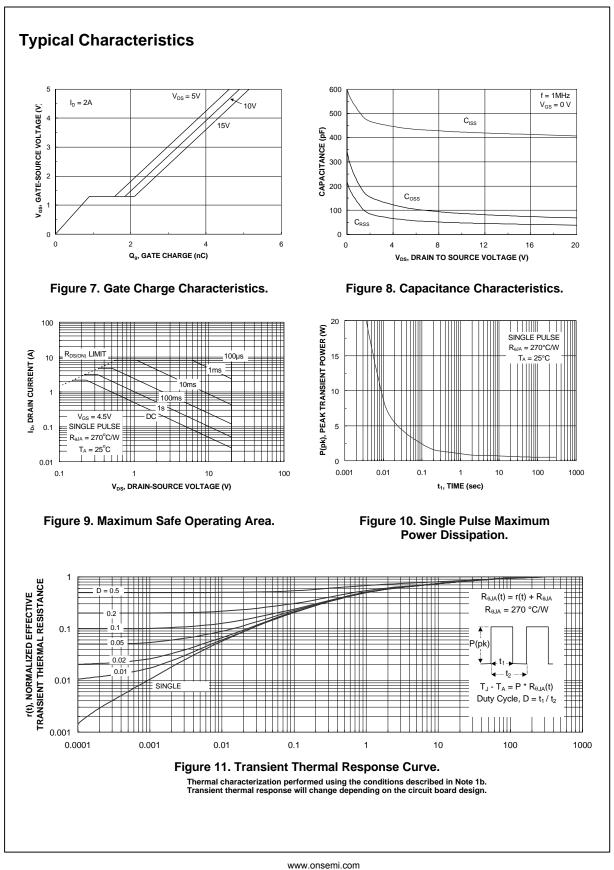
| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|-------------------------------------|--|---|-----|----------------------|------------------------|------------|
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain–Source Breakdown Voltage | $V_{GS} = 0 V$, $I_D = 250 \mu A$ | 20 | | | V |
| <u>ΔBVdss</u> ΔTj | Breakdown Voltage Temperature Coefficient | $I_D = 250 \ \mu\text{A}, \text{Referenced to } 25^{\circ}\text{C}$ | | 12 | | mV/°C |
| DSS | Zero Gate Voltage Drain Current | $V_{\text{DS}} = 16 \text{ V}, \qquad V_{\text{GS}} = 0 \text{ V}$ | | | 1 | μΑ |
| GSSF | Gate-Body Leakage, Forward | $V_{GS} = 8 V$, $V_{DS} = 0 V$ | | | 100 | nA |
| GSSR | Gate-Body Leakage, Reverse | $V_{GS} = -8 V$, $V_{DS} = 0 V$ | | | -100 | nA |
| On Char | acteristics (Note 2) | · | | | • | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$ | 0.4 | 0.7 | 1.5 | V |
| $\Delta V_{GS(th)}$ ΔT_J | Gate Threshold Voltage Temperature Coefficient | $I_D = 250 \ \mu\text{A}, \text{Referenced to } 25^{\circ}\text{C}$ | | -3 | | mV/°C |
| R _{DS(on)} | Static Drain–Source On–Resistance | $ \begin{array}{l} V_{GS} = 4.5 \ V, I_D = 2.0 \ A \\ V_{GS} = 2.5 \ V, I_D = 1.9 \ A \\ V_{GS} = 1.8 \ V, I_D = 1.6 \ A \\ V_{GS} = 4.5 \ V, \ I_D = 2 \ A, \ T_J = 125^\circ C \end{array} $ | | 40 49 65 55 | 70 80 120 103 | mΩ |
| D(on) | On–State Drain Current | $V_{GS} = 4.5V, \qquad V_{DS} = 5V$ | 8 | | | Α |
| 9 _{FS} | Forward Transconductance | $V_{DS} = 5V$, $I_D = 2A$ | | 11 | | S |
| - | Characteristics | | | | | |
| Ciss | Input Capacitance | $V_{DS} = 10 V$, $V_{GS} = 0 V$ | | 423 | | pF |
| C _{oss} | Output Capacitance | f = 1.0 MHz | | 87 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 48 | | pF |
| Switchin | g Characteristics (Note 2) | | | | | |
| d(on) | Turn–On Delay Time | $V_{DD} = 10 V, \qquad I_D = 1 A,$ | | 6 | 12 | ns |
| r | Turn–On Rise Time | $V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$ | | 6.5 | 13 | ns |
| d(off) | Turn–Off Delay Time | | | 14 | 29 | ns |
| ł | Turn–Off Fall Time | - | | 2 | 4 | ns |
| Qg | Total Gate Charge | $V_{DS} = 10 V$, $I_{D} = 2 A$, | | 4.5 | 6.3 | nC |
| Q _{gs} | Gate-Source Charge | V _{GS} = 4.5 V | | 0.89 | | nC |
| Q _{gd} | Gate-Drain Charge | 7 | | 0.95 | | nC |
| Drain-S | ource Diode Characteristics | and Maximum Ratings | | | | |
| s | Maximum Continuous Drain-Source | Diode Forward Current | | | 0.42 | А |
| V_{SD} | Drain–Source Diode Forward Voltage | $V_{GS} = 0 V$, $I_S = 0.42 A$ (Note 2) | | 0.6 | 1.2 | V |
| | um of the junction-to-case and case-to-ambient the s. R _{6JC} is guaranteed by design while R _{6CA} is dete a) 250°C/W when mounted on a 0.02 in pad of 2 oz. copper. | | | d as the sol | der mounti | ng surface |

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%



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